

ABSTRACT

COVER TAPE AND ELECTRONIC COMPONENT PACKAGING BODY INCLUDING SAME

The present invention addresses a problem of providing a cover tape for which there is a low risk of an electronic component adhering to the cover tape when the cover tape is peeled in order to extract the electronic component.

Provided is a cover tape having an insulating heat seal layer provided on one surface and a conductive layer laminated directly on the heat seal layer, wherein: the surface resistivity on the heat seal layer-side is $1 \times 10^{10} \Omega/\square$ or less; and the average thickness of the heat seal layer is less than 600 nm.

Figure 1